

TIN, LEAD OR TIN/LEAD ALLOY ELECTROLYTES
FOR HIGH SPEED ELECTROPLATING

ABSTRACT

An electrolyte, system and process for depositing tin, lead or tin/lead alloys upon a substrate by high speed electroplating, which includes a basis solution of an alkyl or alkylol sulfonic acid; and at least one of a solution soluble tin compound or a solution soluble lead compound; and an alkylene oxide condensation compound of an organic compound having no more than twenty carbon atoms in one or two independent or joined rings optionally substituted with an alkyl moiety of eight carbon atoms or less.

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